

PATENT ABSTRACTS OF JAPAN

(11)Publication number : **2002-111215**

(43)Date of publication of application : **12.04.2002**

(51)Int.Cl.

H05K 3/46

C08J 5/08

H01L 23/14

H05K 1/11

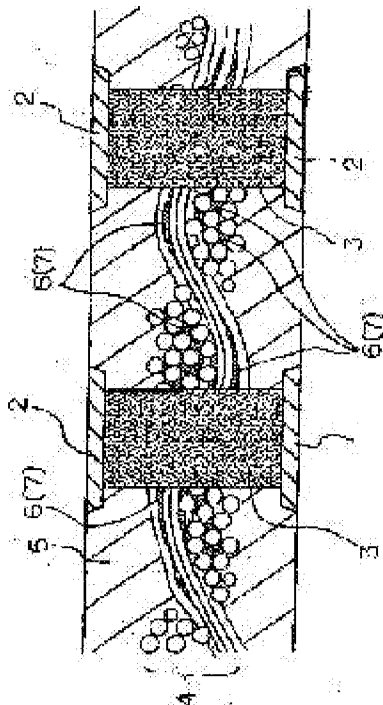
H05K 3/40

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(21)Application number : **2000-296946** (71)Applicant : **KYOCERA CORP**

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(54) WIRING BOARD AND ITS MANUFACTURING METHOD



(57)Abstract:

PROBLEM TO BE SOLVED: To provide a wiring board which contains insulating layers made of a composite material of a heat-resistant woven fabric and a thermosetting resin and has superior insulation reliability between via hole conductors even when the conductors are formed at narrow intervals of $\leq 500 \mu\text{m}$, and to provide a method of manufacturing the board.

SOLUTION: The wiring board is provided with the insulating layers 1 made of a composite material composed of the heat-resistant woven fabric 4, such as the glass woven fabric, etc., and the thermosetting resin 5, a plurality of conductor circuit layers 2 formed on and between the insulating layers 1, and the via hole conductors 3 which are formed by impregnating metallic powder packed in via holes with conductor paste so that the minimum interval between the conductors 3 may become $\leq 500 \mu\text{m}$. Before the

metallic powder is impregnated with the conductor paste, a liquid resin 7 is impregnated

into and cured in the voids 6 among the fibers of the heat-resistant woven fabric 4 around the via hole conductors 3.